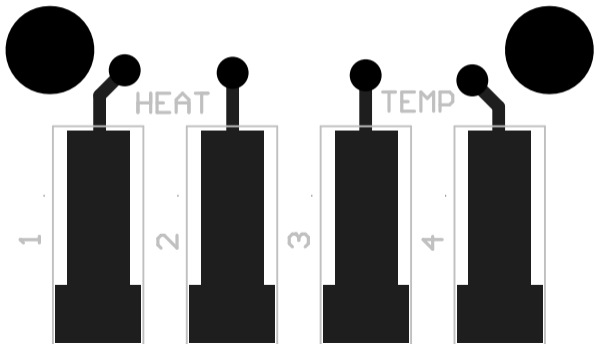


HYDRA RESEARCH  
TOOL PCB REV0.4





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HEAT



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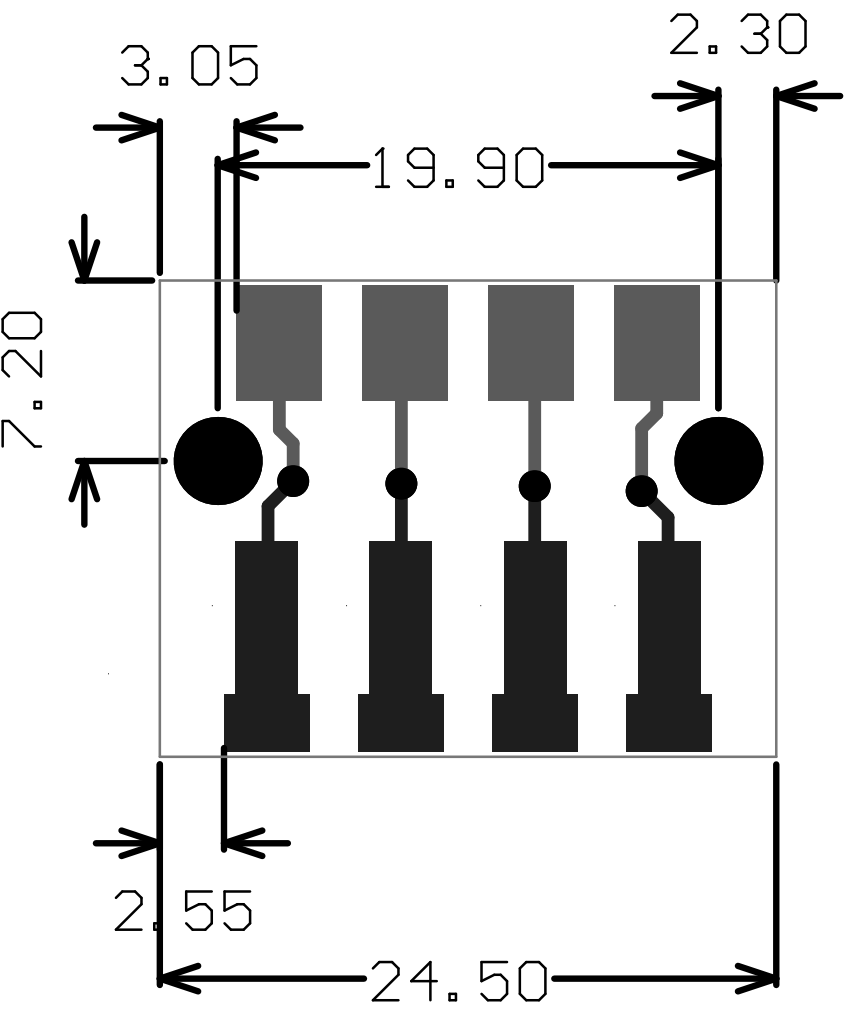


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TEMP



Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad	Pad Shape	Template	Description	Hole Tolerance (+)	Hole Tolerance (-)
□	2	98.43mil (2.500mm)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c350h250			
○	4	28.00mil (0.711mm)	PTH	Round	Top Layer - Bottom Layer	Via	Rounded	v127h71			
	6 Total										



Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.39mil	3.5	
3	Top Layer	Copper	1.38mil		
4	Dielectric 1	FR-4	59.06mil	4.8	
5	Bottom Layer	Copper	1.38mil		
6	Bottom Solder	Solder Resist	0.39mil	3.5	
7	Bottom Overlay				

